

Typical Applications

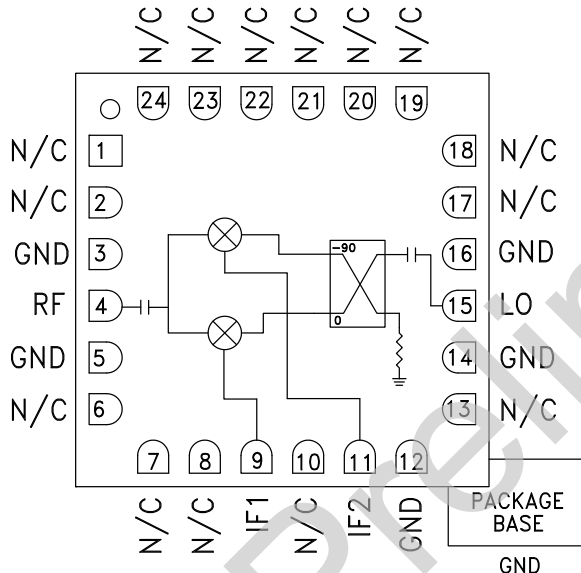
The HMC525ALC4 is ideal for:

- Point-to-Point and Point-to-Multi-Point Radio
- VSAT

Features

- Wide IF Bandwidth: DC - 3.5 GHz
- Image Rejection: 40 dB
- LO to RF Isolation: 50 dB
- High Input IP3: +23 dBm
- 24 Lead 4x4mm SMT Package: 16mm²

Functional Diagram



General Description

The HMC525ALC4 is a compact I/Q MMIC mixer in a leadless "Pb free" RoHS compliant SMT package, which can be used as either an Image Reject Mixer or a Single Sideband Upconverter. The mixer utilizes two standard Hittite double balanced mixer cells and a 90 degree hybrid fabricated in a GaAs MESFET process. A low frequency quadrature hybrid was used to produce a 100 MHz USB IF output. This product is a much smaller alternative to hybrid style Image Reject Mixers and Single Sideband Upconverter assemblies. The HMC525ALC4 eliminates the need for wire bonding allowing use of surface mount manufacturing techniques.

Electrical Specifications, $T_A = +25^\circ\text{C}$, IF = 100 MHz, LO = +15 dBm*

Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range, RF/LO		4.0 - 8.5			5.5 - 7.5		GHz
Frequency Range, IF		DC - 3.5			DC - 3.5		GHz
Conversion Loss (As IRM)		8	11		7.5	9.5	dB
Image Rejection	20	35		30	40		dB
1 dB Compression (Input)		+14			+15		dBm
LO to RF Isolation	33	45		40	50		dB
LO to IF Isolation	14	20		17	20		dB
IP3 (Input)		+23			+23		dBm
Amplitude Balance		0.3			0.2		dB
Phase Balance		8			4		Deg

* Unless otherwise noted, all measurements performed as downconverter.

**GaAs MMIC I/Q MIXER
4 - 8.5 GHz**
Harmonics of LO

LO Freq. (GHz)	nLO Spur at RF Port			
	1	2	3	4
3.5	40	40	54	50
4.5	43	45	58	53
5.5	51	57	48	67
6.5	59	63	64	56
7.5	48	66	64	62
8.5	44	65	60	67

LO = +15 dBm
Values in dBc below input LO level measured at RF Port.

MxN Spurious Outputs

mRF	nLO				
	0	1	2	3	4
0	xx	-11	32	23	51
1	32	0	42	51	66
2	89	62	74	65	89
3	89	89	89	82	89
4	89	89	89	89	89

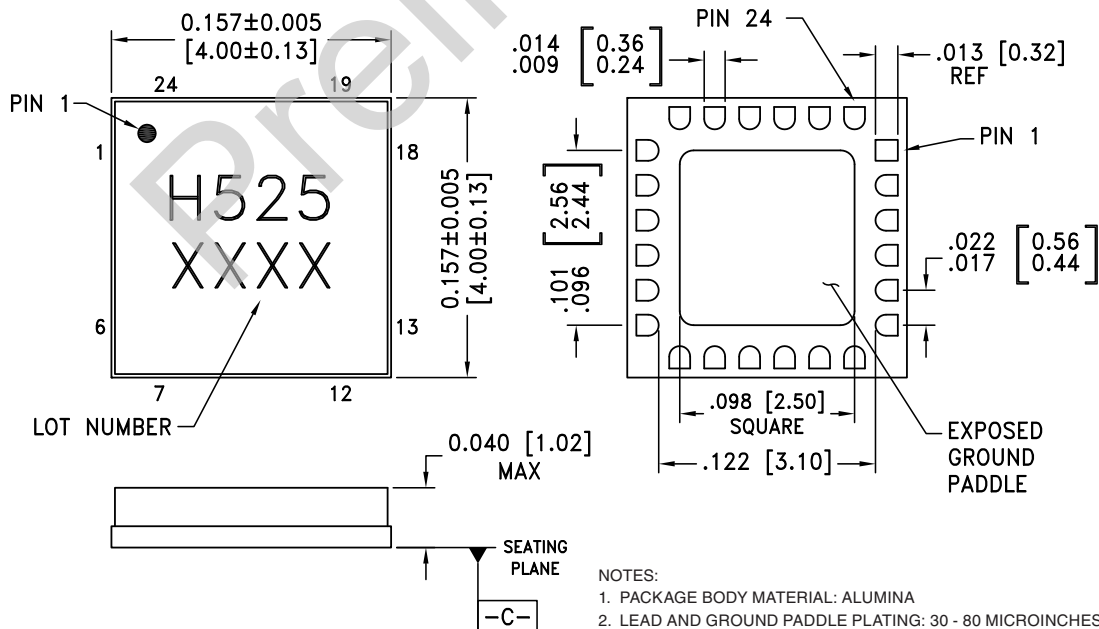
RF = 5.6 GHz @ -10 dBm
LO = 5.5 GHz @ +15 dBm
Data taken without IF hybrid
All values in dBc below IF power level

Absolute Maximum Ratings

RF / IF Input	+20 dBm
LO Drive	+27 dBm
Channel Temperature	150°C
Continuous P _{diss} (T=85°C) (derate 9.7 mW/°C above 85°C)	631 mW
Thermal Resistance (R _{TH}) (junction to die bottom)	103 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Outline Drawing
BOTTOM VIEW

NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING: 30 - 80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKLE
3. DIMENSIONS ARE IN INCHES [MILLIMETERS]
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND